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# **FDC3612**

# 100V N-Channel PowerTrench® MOSFET

### **General Description**

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low  $R_{\text{DS(ON)}}$  and fast switching speed.

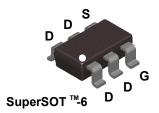
### **Applications**

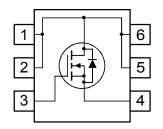
DC/DC converter

#### **Features**

• 2.6 A, 100 V  $R_{DS(ON)} = 125 \text{ m}\Omega$  @  $V_{GS} = 10 \text{ V}$   $R_{DS(ON)} = 135 \text{ m}\Omega$  @  $V_{GS} = 6 \text{ V}$ 

- High performance trench technology for extremely low  $R_{\mbox{\scriptsize DS}(\mbox{\scriptsize ON})}$
- Low gate charge (14nC typ)
- High power and current handling capability
- · Fast switching speed





## Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage		100	V
V <sub>GSS</sub>	Gate-Source Voltage		± 20	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	2.6	A
	<ul><li>Pulsed</li></ul>		20	
E <sub>AS</sub>	Single Pulse Avalanche Energy	(Note 3)	37	mJ
P <sub>D</sub>	Maximum Power Dissipation	(Note 1a)	1.6	W
		(Note 1b)	0.8	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temporal	erature Range	-55 to +150	°C

### **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	78	°C/W
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	30	°C/W

**Package Marking and Ordering Information** 

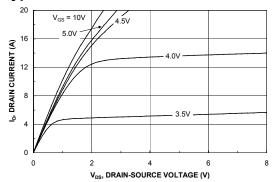
Device Marking	Device	Reel Size	Tape width	Quantity
.362	FDC3612	7"	8mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	urce Avalanche Ratings (Note	22)				
W <sub>DSS</sub>	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 50 \text{ V}$ , $I_D = 2.6 \text{ A}$			90	mJ
I <sub>AR</sub>	Drain-Source Avalanche Current	3 - 3 - 1 - 1 - 1			2.6	Α
	acteristics		l		II.	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 250 μA	100			V
$\Delta BV_{DSS}$ $\Delta T_{,l}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 250 $\mu$ A, Referenced to 25°C		99		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V			10	μΑ
I <sub>GSSF</sub>	Gate–Body Leakage, Forward	V <sub>GS</sub> = 20 V, V <sub>DS</sub> = 0 V			100	nA
I <sub>GSSR</sub>	Gate–Body Leakage, Reverse	$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)		ı		I	ı
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2	2.3	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I <sub>D</sub> = 250 μA, Referenced to 25°C		- 6		mV/°C
R <sub>DS(on)</sub>	Static Drain–Source On Resistance	$V_{GS} = 10 \text{ V}, \ I_D = 2.6 \text{ A}$ $V_{GS} = 6.0 \text{ V}, \ I_D = 2.5 \text{ A}$ $V_{GS} = 10 \text{ V}, \ I_D = 2.6 \text{ A}; T_J = 125^{\circ}\text{C}$		86 91 157	125 135 240	mΩ
I <sub>D(on)</sub>	On-State Drain Current	V <sub>GS</sub> = 10 V, V <sub>DS</sub> = 5 V	10			Α
<b>g</b> <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 2.6 A		10		S
Dvnamio	Characteristics		,			
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V,		660		pF
Coss	Output Capacitance	f = 1.0 MHz		55		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	1		40		pF
R <sub>g</sub>	Gate Resistance		0.1	1.4	3.0	Ω
Switchin	g Characteristics (Note 2)		•	•		•
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 1 A,		6	11	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \qquad R_{GEN} = 6 \Omega$		3.5	7	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			23	37	ns
t <sub>f</sub>	Turn-Off Fall Time			3.7	7.4	ns
$Q_g$	Total Gate Charge	$V_{DS} = 50 \text{ V}, \qquad I_{D} = 2.6 \text{ A},$		14	20	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>GS</sub> = 10 V		2.3		nC
$Q_{gd}$	Gate-Drain Charge			3.6		nC
	ource Diode Characteristics	and Maximum Ratings	,			
I <sub>s</sub>	Maximum Continuous Drain–Source	<u> </u>			1.3	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 1.3 A (Note 2)		0.76	1.2	V
t <sub>rr</sub>	Diode Reverse Recovery Time	I <sub>F</sub> = 2.6 A		31		nS
Q <sub>rr</sub>	Diode Reverse Recovery Charge	$d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$ (Note 2)		56		nC

#### Notes:

- 1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.
- a. 78°C/W when mounted on a 1in² pad of 2oz copper on FR-4 board.
- b. 156°C/W when mounted on a minimum pad.
- 2. Pulse Test: Pulse Width  $\leq 300~\mu\text{s},~\text{Duty Cycle} \leq 2.0\%$
- 3.  $E_{AS}$  of 37 mJ is based on starting  $T_J$  = 25 °C; N-ch: L = 3 mH,  $I_{AS}$  = 5 A,  $V_{DD}$  = 100 V,  $V_{QS}$  = 10 V. 100% test at L = 0.3 mH,  $I_{AS}$  = 11 A.

# **Typical Characteristics**



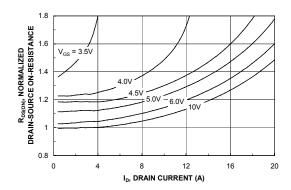
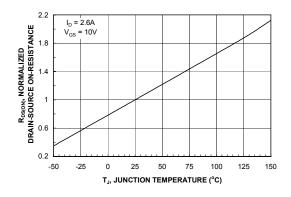


Figure 1. On-Region Characteristics.

Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.



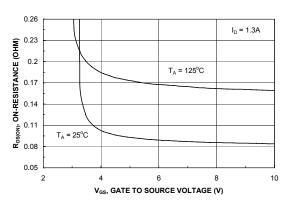
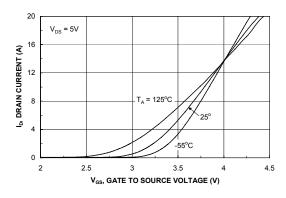


Figure 3. On-Resistance Variation with Temperature.

Figure 4. On-Resistance Variation with Gate-to-Source Voltage.



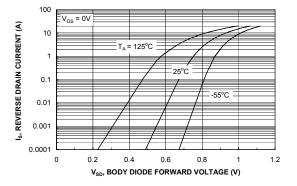
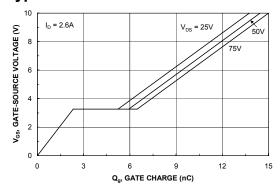


Figure 5. Transfer Characteristics.

Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

# **Typical Characteristics**



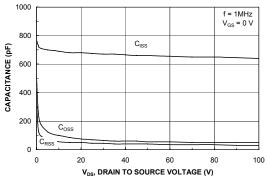


Figure 7. Gate Charge Characteristics.

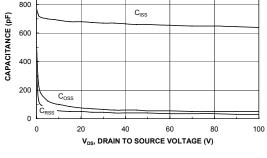
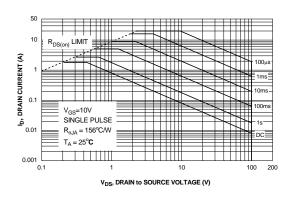


Figure 8. Capacitance Characteristics.



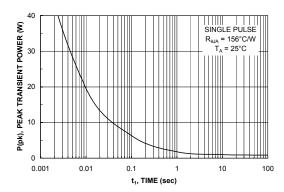


Figure 9. Maximum Safe Operating Area.



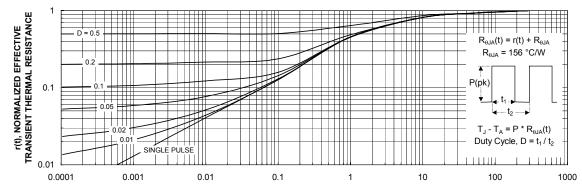
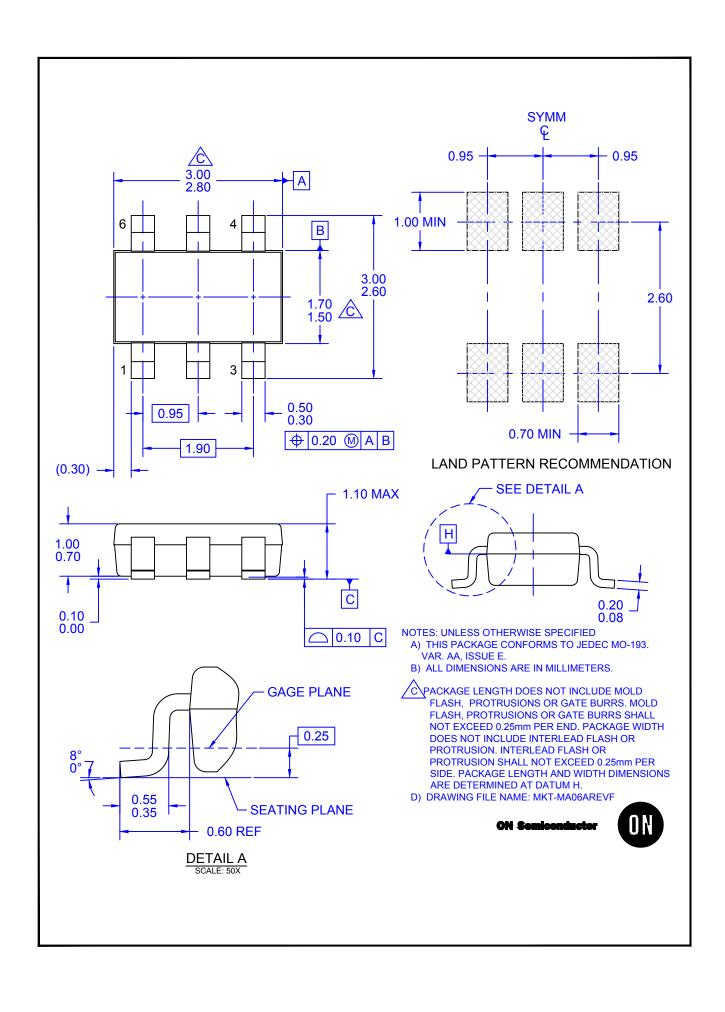


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.



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